




PCN Number:	20200914001.1		PCN Date:	Sept 16, 2020	
Title:	Qualification of TI Mexico as a new assembly site for select Devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Dec 16, 2020	Estimated Sample Availability:	Date provided at sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
<p>Texas Instruments Incorporated is announcing the qualification of TI Mexico as a new Assembly site for devices listed below in the product affected section. There are no construction differences between the current and new assembly sites, but there are device symbolization differences as follows:</p>					
	FXC	TI Mexico			
Lid Marking	Sticker Label	Laser Mark			
CC3100MOD Lid Marking sample					
CC3200MOD Lid Marking sample					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					

Anticipated impact on Material Declaration

<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp
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Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
Foxconn	FXC	CHN	Chongqing
TI Mexico	MEX	MEX	Aguascalientes

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: GHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

CC3100MODR11MAMOBR	CC3200MODR1M2AMOBR
CC3100MODR11MAMOBT	CC3200MODR1M2AMOBT

Qualification Report

Approved 14-Sep-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>CC3100MODR11MAMOB</u>	QBS Product Reference: <u>CC3100MODR11MAMOB</u>	QBS Package Reference: <u>CC3235MODSF12MOB</u>
TC	Temperature Cycle, -40/105C	500 Cycles	1/45/0	1/45/0	-
TC	Temperature Cycle, -40/125C	400 Cycles	-	-	1/45/0
UH	Unbiased Temperature and Humidity, 85C/85%RH	500 Hours	1/45/0	1/45/0	-
CDM	ESD CDM	250 V	1/3/0	1/3/0	-
HTSL	High Temp. Storage Bake, 100C	500 Hours	-	1/45/0	-
SD	Solderability	Solderability	-	1/5/0	1/5/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	-	1/5/0

- QBS: Qualification By Similarity

- Preconditioning was performed for Temperature Cycle, Unbiased Temperature and Humidity, High Temp. Storage Bake, and Biased Temperature and Humidity.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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